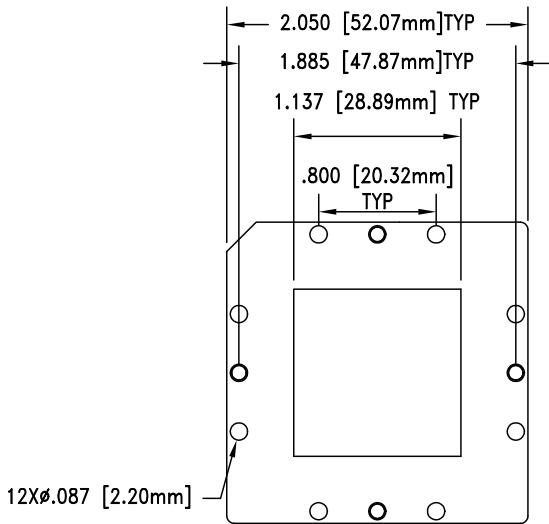
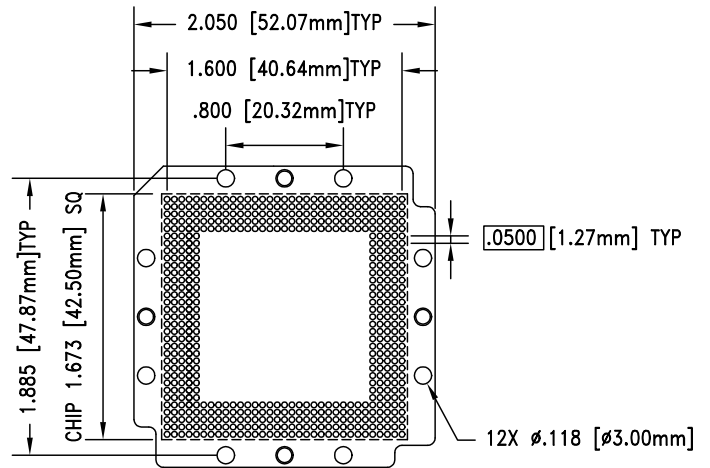


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	4/28/00	M.D.
B	UPDATED PAD LAYOUT AND DIMS	03/30/01	H.N.
C	ADDED CHIP SIZE	03/25/02	H.N.

SKT781
DOD 4781



RETENTION FRAME

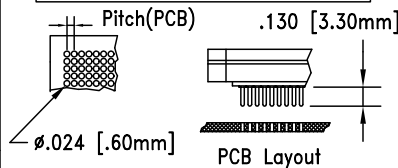
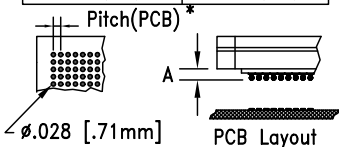


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET) YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

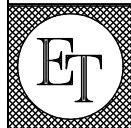
PIN DIAMETER FOR:
-70(ET) = .018 [0.45mm]

* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 560
LEAD PITCH	= 1.27mm
GRID SIZE	= 33X33
PACKAGE SIZE	= 42.50mm SQ

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg. F
Santa Clara, Ca 95051

TEL:(408)982-0660
FAX:(408)982-0664

SHEET: 1 OF 1
DATE: 03/25/02

REVISION: C

ASSEMBLY DRAWING

CHECKED:
Perry Munroe

DRAWN:
Huy Nguyen

ITEM: S-BGA-33-560-XX

DO NOT SCALE DRAWING

DESCRIPTION:
BPW-560-2BG033-YY